

### Features

- 'HC161, 'HCT161 4-Bit Binary Counter, Asynchronous Reset
- 'HC163, 'HCT163 4-Bit Binary Counter, Synchronous Reset
- Synchronous Counting and Loading
- Two Count Enable Inputs for n-Bit Cascading
- Look-Ahead Carry for High-Speed Counting
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Description

The 'HC161, 'HCT161, 'HC163, and 'HCT163 are presettable synchronous counters that feature look-ahead carry logic for use in high-speed counting applications. The 'HC161 and 'HCT161 are asynchronous reset decade and binary counters, respectively; the 'HC163 and 'HCT163 devices are decade and binary counters, respectively, that are reset synchronously with the clock. Counting and parallel presetting are both accomplished synchronously with the negative-to-positive transition of the clock.

A low level on the synchronous parallel enable input, SPE, disables counting operation and allows data at the P0 to P3 inputs to be loaded into the counter (provided that the setup and hold requirements for SPE are met).

All counters are reset with a low level on the Master Reset input, MR. In the 'HC163 and 'HCT163 counters (synchronous reset types), the requirements for setup and hold time with respect to the clock must be met.

Two count enables, PE and TE, in each counter are provided for n-bit cascading. In all counters reset action occurs regardless of the level of the  $\overline{SPE}$ , PE and TE inputs (and the clock input, CP, in the 'HC161 and 'HCT161 types).

If a decade counter is preset to an illegal state or assumes an illegal state when power is applied, it will return to the normal sequence in one count as shown in state diagram.

The look-ahead carry feature simplifies serial cascading of the counters. Both count enable inputs (PE and TE) must be high to count. The TE input is gated with the Q outputs of all four stages so that at the maximum count the terminal count (TC) output goes high for one clock period. This TC pulse is used to enable the next cascaded stage.

### Ordering Information

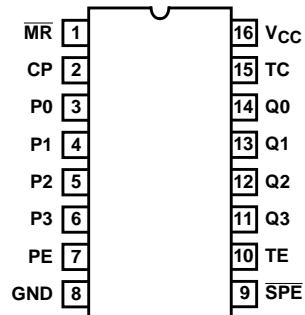
PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC161F3A	-55 to 125	16 Ld CERDIP
CD54HC163F3A	-55 to 125	16 Ld CERDIP
CD54HCT163F3A	-55 to 125	16 Ld CERDIP
CD74HC161E	-55 to 125	16 Ld PDIP
CD74HC161M	-55 to 125	16 Ld SOIC
CD74HC161MT	-55 to 125	16 Ld SOIC
CD74HC161M96	-55 to 125	16 Ld SOIC
CD74HC163E	-55 to 125	16 Ld PDIP
CD74HC163M	-55 to 125	16 Ld SOIC
CD74HC163MT	-55 to 125	16 Ld SOIC
CD74HC163M96	-55 to 125	16 Ld SOIC
CD74HCT161E	-55 to 125	16 Ld PDIP
CD74HCT161M	-55 to 125	16 Ld SOIC
CD74HCT161MT	-55 to 125	16 Ld SOIC
CD74HCT161M96	-55 to 125	16 Ld SOIC
CD74HCT163E	-55 to 125	16 Ld PDIP
CD74HCT163M	-55 to 125	16 Ld SOIC
CD74HCT163MT	-55 to 125	16 Ld SOIC
CD74HCT163M96	-55 to 125	16 Ld SOIC

NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel. The suffix T denotes a small-quantity reel of 250.

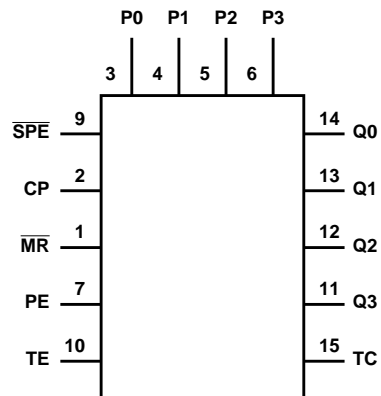
# CD54/74HC161, CD54/74HCT161, CD54/74HC163, CD54/74HCT163

## Pinout

CD54HC161, CD54HCT161, CD54HC163, CD54HCT163  
(CERDIP)  
CD74HC161, CD74HCT161, CD74HC163, CD74HCT163  
(PDIP, SOIC)  
TOP VIEW



## Functional Diagram



**CD54/74HC161, CD54/74HCT161, CD54/74HC163, CD54/74HCT163**

**MODE SELECT - FUNCTION TABLE FOR 'HC161 AND 'HCT161**

OPERATING MODE	INPUTS						OUTPUTS	
	$\overline{MR}$	CP	PE	TE	$\overline{SP\overline{E}}$	$P_n$	$Q_n$	TC
Reset (Clear)	L	X	X	X	X	X	L	L
Parallel Load	H	↑	X	X	l	l	L	L
	H	↑	X	X	l	h	H	(Note 1)
Count	H	↑	h	h	h (Note 3)	X	Count	(Note 1)
Inhibit	H	X	l (Note 2)	X	h (Note 3)	X	$q_n$	(Note 1)
	H	X	X	l (Note 2)	h (Note 3)	X	$q_n$	L

**MODE SELECT - FUNCTION TABLE FOR 'HC163 AND 'HCT163**

OPERATING MODE	INPUTS						OUTPUTS	
	$\overline{MR}$	CP	PE	TE	$\overline{SP\overline{E}}$	$P_n$	$Q_n$	TC
Reset (Clear)	l	↑	X	X	X	X	L	L
Parallel Load	h (Note 3)	↑	X	X	l	l	L	L
	h (Note 3)	↑	X	X	l	h	H	(Note 1)
Count	h (Note 3)	↑	h	h	h (Note 3)	X	Count	(Note 1)
Inhibit	h (Note 3)	X	l (Note 2)	X	h (Note 3)	X	$q_n$	(Note 1)
	h (Note 3)	X	X	l (Note 2)	h (Note 3)	X	$q_n$	L

H = High voltage level steady state; L = Low voltage level steady state; h = High voltage level one setup time prior to the Low-to-High clock transition; l = Low voltage level one setup time prior to the Low-to-High clock transition; X = Don't Care; q = Lower case letters indicate the state of the referenced output prior to the Low-to-High clock transition; ↑ = Low-to-High clock transition.

**NOTES:**

1. The TC output is High when TE is High and the counter is at Terminal Count (HHHH for HC/HCT161 and 'HC/HCT163).
2. The High-to-Low transition of PE or TE on the 'HC/HCT161 and the 'HC/HCT163 should only occur while CP is HIGH for conventional operation.
3. The Low-to-High transition of  $\overline{SP\overline{E}}$  on the 'HC/HCT161 and  $\overline{SP\overline{E}}$  or  $\overline{MR}$  on the 'HC/HCT163 should only occur while CP is HIGH for conventional operation.

# CD54/74HC161, CD54/74HCT161, CD54/74HC163, CD54/74HCT163

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$ .....	-0.5V to 7V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Drain Current, per Output, $I_O$	
For $-0.5V < V_O < V_{CC} + 0.5V$ .....	$\pm 25mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....	$\pm 25mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ .....	$\pm 50mA$

## Thermal Information

Thermal Resistance (Typical, Note 4)	$\theta_{JA}$ ( $^{\circ}C/W$ )
E (PDIP) Package .....	67
M (SOIC) Package .....	73
Maximum Junction Temperature .....	150 $^{\circ}C$
Maximum Storage Temperature Range .....	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s) .....	300 $^{\circ}C$ (SOIC - Lead Tips Only)

## Operating Conditions

Temperature Range, $T_A$ .....	-55 $^{\circ}C$ to 125 $^{\circ}C$
Supply Voltage Range, $V_{CC}$	
HC Types .....	.2V to 6V
HCT Types .....	4.5V to 5.5V
DC Input or Output Voltage, $V_I, V_O$ .....	0V to $V_{CC}$
Input Rise and Fall Time	
2V .....	1000ns (Max)
4.5V .....	500ns (Max)
6V .....	400ns (Max)

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

### NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25 $^{\circ}C$			-40 $^{\circ}C$ TO 85 $^{\circ}C$		-55 $^{\circ}C$ TO 125 $^{\circ}C$		UNITS	
		$V_I$ (V)	$I_O$ (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX		
<b>HC TYPES</b>													
High Level Input Voltage	$V_{IH}$	-	-	2	1.5	-	-	1.5	-	1.5	-	V	
				4.5	3.15	-	-	3.15	-	3.15	-	V	
				6	4.2	-	-	4.2	-	4.2	-	V	
Low Level Input Voltage	$V_{IL}$	-	-	2	-	-	0.5	-	0.5	-	0.5	V	
				4.5	-	-	1.35	-	1.35	-	1.35	V	
				6	-	-	1.8	-	1.8	-	1.8	V	
High Level Output Voltage CMOS Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.02	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-	-	-	-	-	-	-	-	-	V	
			-4	-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	0.02	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	-	-	-	-	-	-	-	-	-	V	
			4	4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	$I_I$	$V_{CC}$ or GND	-	6	-	-	$\pm 0.1$	-	$\pm 1$	-	$\pm 1$	$\mu A$	

**CD54/74HC161, CD54/74HCT161, CD54/74HC163, CD54/74HCT163**

**DC Electrical Specifications (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	6	-	-	8	-	80	-	160	μA
<b>HCT TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> and GND	0	5.5	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub> (Note 5)	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA

NOTE:

5. For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

**HCT Input Loading Table**

INPUT	UNIT LOADS
P0 - P3	0.25
PE	0.65
CP	1.05
MR	0.8
SPE	0.5
TE	1.05

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Table, e.g., 360μA max at 25°C.

**CD54/74HC161, CD54/74HCT161, CD54/74HC163, CD54/74HCT163**

**Prerequisite For Switching Specifications**

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>											
Maximum CP Frequency (Note 6)	f <sub>MAX</sub>	-	2	6	-	-	5	-	4	-	MHz
			4.5	30	-	-	24	-	20	-	MHz
			6	35	-	-	28	-	24	-	MHz
CP Width (Low)	t <sub>W(L)</sub>	-	2	80	-	-	100	-	120	-	ns
			4.5	16	-	-	20	-	24	-	ns
			6	14	-	-	17	-	20	-	ns
MR Pulse Width (161)	t <sub>W</sub>	-	2	100	-	-	125	-	150	-	ns
			4.5	20	-	-	25	-	30	-	ns
			6	17	-	-	21	-	26	-	ns
Setup Time, Pn to CP	t <sub>SU</sub>	-	2	60	-	-	75	-	90	-	ns
			4.5	12	-	-	15	-	18	-	ns
			6	10	-	-	13	-	15	-	ns
Setup Time, PE or TE to CP	t <sub>SU</sub>	-	2	50	-	-	65	-	75	-	ns
			4.5	10	-	-	13	-	15	-	ns
			6	9	-	-	11	-	13	-	ns
Setup Time, SPE to CP	t <sub>SU</sub>	-	2	60	-	-	75	-	90	-	ns
			4.5	12	-	-	15	-	18	-	ns
			6	10	-	-	13	-	15	-	ns
Setup Time, MR to CP (163)	t <sub>SU</sub>	-	2	65	-	-	80	-	100	-	ns
			4.5	13	-	-	16	-	20	-	ns
			6	11	-	-	14	-	17	-	ns
Hold Time, PN to CP	t <sub>H</sub>	-	2	3	-	-	3	-	3	-	ns
			4.5	3	-	-	3	-	3	-	ns
			6	3	-	-	3	-	3	-	ns
Hold Time, TE or PE to CP	t <sub>H</sub>	-	2	0	-	-	0	-	0	-	ns
			4.5	0	-	-	0	-	0	-	ns
			6	0	-	-	0	-	0	-	ns
Hold Time, SPE to CP	t <sub>H</sub>	-	2	0	-	-	0	-	0	-	ns
			4.5	0	-	-	0	-	0	-	ns
			6	0	-	-	0	-	0	-	ns
Recovery Time, MR to CP (161)	t <sub>REC</sub>	-	2	75	-	-	95	-	110	-	ns
			4.5	15	-	-	19	-	22	-	ns
			6	13	-	-	16	-	19	-	ns

**CD54/74HC161, CD54/74HCT161, CD54/74HC163, CD54/74HCT163**

**Prerequisite For Switching Specifications (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HCT TYPES</b>											
Maximum CP Frequency	f <sub>MAX</sub>	-	4.5	30	-	-	24	-	20	-	MHz
CP Width (Low) (Note 6)	t <sub>W(L)</sub>	-	4.5	16	-	-	20	-	24	-	ns
$\overline{MR}$ Pulse Width (161)	t <sub>W</sub>	-	4.5	20	-	-	25	-	30	-	ns
Setup Time, Pn to CP	t <sub>SU</sub>	-	4.5	10	-	-	13	-	15	-	ns
Setup Time, PE or TE to CP	t <sub>SU</sub>	-	4.5	13	-	-	16	-	20	-	ns
Setup Time, $\overline{SPE}$ to CP	t <sub>SU</sub>	-	4.5	12	-	-	15	-	18	-	ns
Setup Time, $\overline{MR}$ to CP (163)	t <sub>SU</sub>	-	4.5	13	-	-	16	-	20	-	ns
Hold Time, PN to CP	t <sub>H</sub>	-	4.5	5	-	-	5	-	5	-	ns
Hold Time, TE or PE to CP	t <sub>H</sub>	-	4.5	3	-	-	3	-	3	-	ns
Hold Time, $\overline{SPE}$ to CP	t <sub>H</sub>	-	4.5	3	-	-	3	-	3	-	ns
Recovery Time, $\overline{MR}$ to CP (161)	t <sub>REC</sub>	-	4.5	15	-	-	19	-	22	-	ns

NOTE:

6. Applies to non-cascaded operation only. With cascaded counters clock to terminal count propagation delays, count enables (PE or TE)-to-clock setup times, and count enables (PE or TE)-to-clock hold times determine maximum clock frequency. For example with these HC devices:

$$f_{MAX} (CP) = \frac{1}{CP\text{-to-TC prop. delay} + TE\text{-to-CP setup} + TE\text{-to-CP Hold}} = \frac{1}{37 + 10 + 0} \approx 21\text{MHz}(\text{min})$$

**Switching Specifications** C<sub>L</sub> = 50pF, Input t<sub>r</sub>, t<sub>f</sub> = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>											
Propagation Delay CP to TC	t <sub>PHL</sub> , t <sub>PLH</sub>	C <sub>L</sub> = 50pF	2	-	-	185	-	230	-	280	ns
			4.5	-	-	37	-	46	-	56	ns
		C <sub>L</sub> = 15pF	5	-	15	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	31	-	39	-	48	ns
CP to Qn	t <sub>PHL</sub> , t <sub>PLH</sub>	C <sub>L</sub> = 50pF	2	-	-	185	-	230	-	280	ns
			4.5	-	-	37	-	46	-	56	ns
		C <sub>L</sub> = 15pF	5	-	15	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	31	-	39	-	48	ns
TE to TC	t <sub>PHL</sub> , t <sub>PLH</sub>	C <sub>L</sub> = 50pF	2	-	-	120	-	150	-	180	ns
			4.5	-	-	24	-	30	-	36	ns
		C <sub>L</sub> = 15pF	5	-	9	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	20	-	26	-	31	ns

**CD54/74HC161, CD54/74HCT161, CD54/74HC163, CD54/74HCT163**

**Switching Specifications**  $C_L = 50\text{pF}$ , Input  $t_r, t_f = 6\text{ns}$  (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	$V_{CC}$ (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$\overline{MR}$ to Qn (161)	$t_{PHL}$	$C_L = 50\text{pF}$	2	-	-	210	-	265	-	315	ns
			4.5	-	-	42	-	53	-	63	ns
		$C_L = 15\text{pF}$	5	-	18	-	-	-	-	-	ns
		$C_L = 50\text{pF}$	6	-	-	36	-	45	-	54	ns
$\overline{MR}$ to TC (161)	$t_{PHL}$	$C_L = 50\text{pF}$	2	-	-	210	-	265	-	315	ns
			4.5	-	-	42	-	53	-	63	ns
		$C_L = 50\text{pF}$	6	-	-	36	-	45	-	54	ns
Output Transition Time	$t_{THL}, t_{TLH}$	$C_L = 50\text{pF}$	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Power Dissipation Capacitance (Notes 7, 8)	$C_{PD}$	-	5	-	60	-	-	-	-	-	pF
Input Capacitance	$C_{IN}$	$C_L = 50\text{pF}$	-	10	-	10	-	10	-	10	pF

**HCT TYPES**

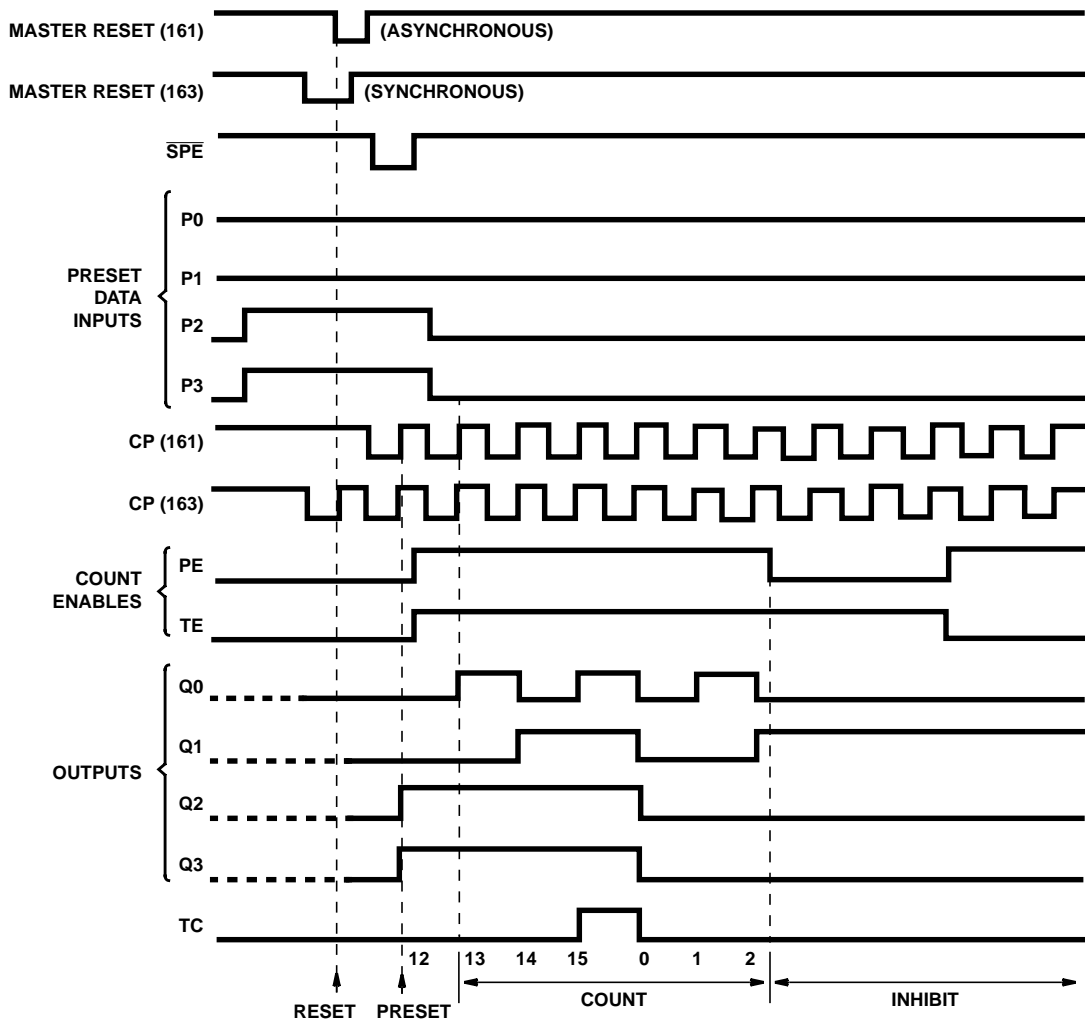
Propagation Delay CP to TC	$t_{PHL}, t_{PLH}$	$C_L = 50\text{pF}$	4.5	-	-	42	-	53	-	63	ns
		$C_L = 15\text{pF}$	5	-	18	-	-	-	-	-	ns
CP to Qn	$t_{PHL}, t_{PLH}$	$C_L = 50\text{pF}$	4.5	-	-	39	-	49	-	59	ns
		$C_L = 15\text{pF}$	5	-	16	-	-	-	-	-	ns
TE to TC	$t_{PHL}, t_{PLH}$	$C_L = 50\text{pF}$	4.5	-	-	32	-	40	-	48	ns
		$C_L = 15\text{pF}$	5	-	13	-	-	-	-	-	ns
$\overline{MR}$ to Qn (161)	$t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	50	-	63	-	75	ns
		$C_L = 15\text{pF}$	5	-	21	-	-	-	-	-	ns
$\overline{MR}$ to TC (161)	$t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	50	-	63	-	75	ns
Output Transition Time	$t_{THL}, t_{TLH}$	$C_L = 50\text{pF}$	4.5	-	-	15	-	19	-	22	ns
Power Dissipation Capacitance (Notes 7, 8)	$C_{PD}$	-	5	-	63	-	-	-	-	-	pF
Input Capacitance	$C_{IN}$	$C_L = 50\text{pF}$	-	10	-	10	-	10	-	10	pF

**NOTES:**

7.  $C_{PD}$  is used to determine the dynamic power consumption, per package.

8.  $P_D = C_{PD} V_{CC}^2 f_i + \sum(C_L V_{CC}^2 f_O)$  where  $f_i$  = Input Frequency,  $f_O$  = Output Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

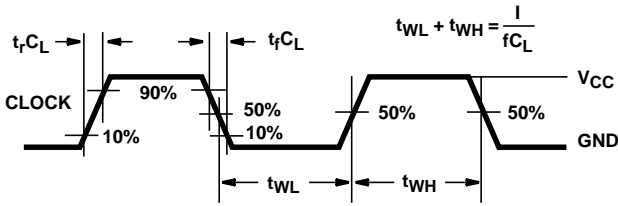
**Timing Diagram**



Sequence illustrated on waveforms:

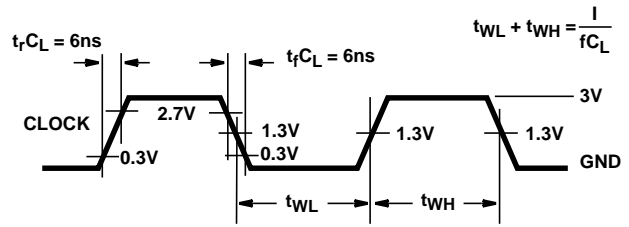
1. Reset outputs to zero.
2. Preset to binary twelve.
3. Count to thirteen, fourteen, fifteen, zero, one, and two.
4. Inhibit.

Test Circuits and Waveforms



NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH



NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

FIGURE 2. HCT CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

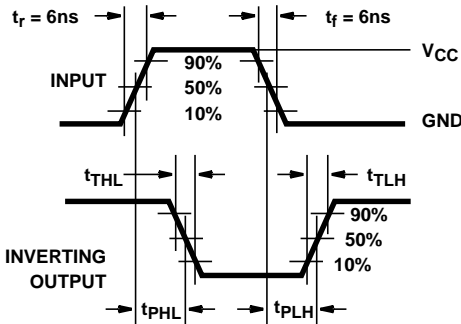


FIGURE 3. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

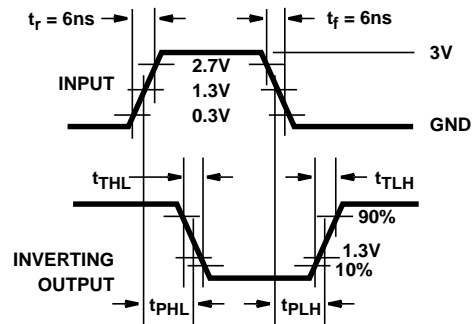


FIGURE 4. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

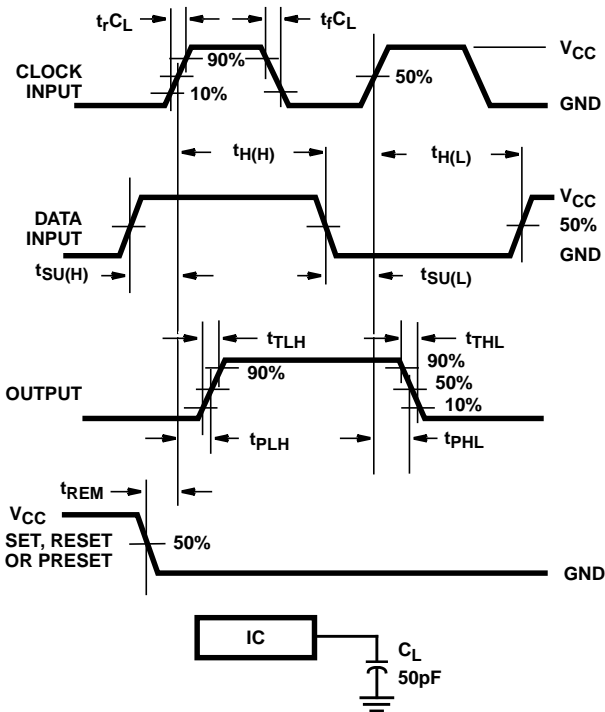


FIGURE 5. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

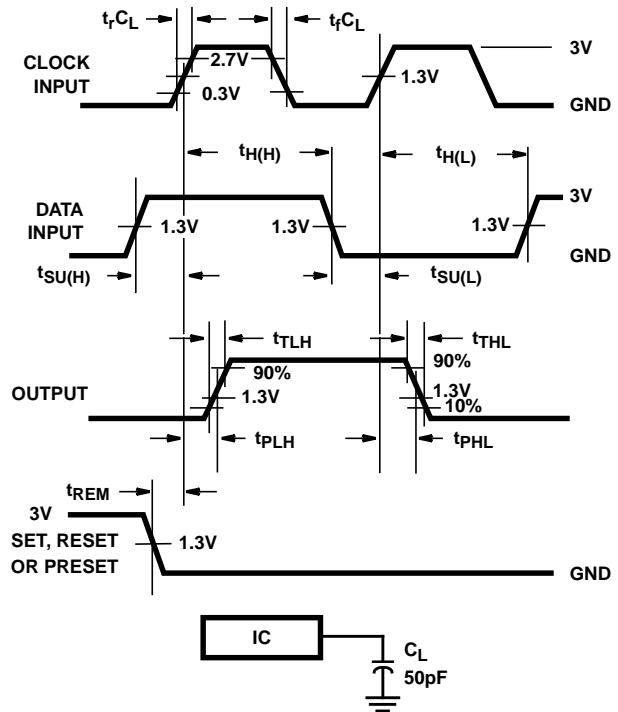


FIGURE 6. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD54HC161F	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD54HC161F	<a href="#">Samples</a>
CD54HC161F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8407501EA CD54HC161F3A	<a href="#">Samples</a>
CD54HC163F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8607601EA CD54HC163F3A	<a href="#">Samples</a>
CD54HCT161F3A	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
CD54HCT163F	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD54HCT163F	<a href="#">Samples</a>
CD54HCT163F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD54HCT163F3A	<a href="#">Samples</a>
CD74HC161E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC161E	<a href="#">Samples</a>
CD74HC161EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC161E	<a href="#">Samples</a>
CD74HC161M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC161M	<a href="#">Samples</a>
CD74HC161M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC161M	<a href="#">Samples</a>
CD74HC161M96E4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC161M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC161M	<a href="#">Samples</a>
CD74HC161ME4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC161MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC161M	<a href="#">Samples</a>
CD74HC161MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC161M	<a href="#">Samples</a>
CD74HC161MTE4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC161MTG4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC163E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC163E	<a href="#">Samples</a>
CD74HC163EE4	ACTIVE	PDIP	N	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HC163M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC163M	<a href="#">Samples</a>
CD74HC163M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC163M	<a href="#">Samples</a>
CD74HC163M96E4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC163M96G4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC163ME4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC163MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC163M	<a href="#">Samples</a>
CD74HC163MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC163M	<a href="#">Samples</a>
CD74HC163MTE4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC163MTG4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT161E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT161E	<a href="#">Samples</a>
CD74HCT161EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT161E	<a href="#">Samples</a>
CD74HCT161M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT161M	<a href="#">Samples</a>
CD74HCT161M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT161M	<a href="#">Samples</a>
CD74HCT161M96E4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT161M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT161M	<a href="#">Samples</a>
CD74HCT161ME4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT161MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT161M	<a href="#">Samples</a>
CD74HCT161MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT161M	<a href="#">Samples</a>
CD74HCT161MTE4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HCT161MTG4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT163E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT163E	<a href="#">Samples</a>
CD74HCT163EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT163E	<a href="#">Samples</a>
CD74HCT163M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT163M	<a href="#">Samples</a>
CD74HCT163M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT163M	<a href="#">Samples</a>
CD74HCT163M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT163M	<a href="#">Samples</a>
CD74HCT163M96G4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT163ME4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT163MG4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT163MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT163M	<a href="#">Samples</a>
CD74HCT163MTE4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT163MTG4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

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**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF CD54HC161, CD54HC163, CD54HCT161, CD54HCT163, CD74HC161, CD74HC163, CD74HCT161, CD74HCT163 :**

● Catalog: [CD74HC161](#), [CD74HC163](#), [CD74HCT161](#), [CD74HCT163](#)

● Military: [CD54HC161](#), [CD54HC163](#), [CD54HCT161](#), [CD54HCT163](#)

NOTE: Qualified Version Definitions:

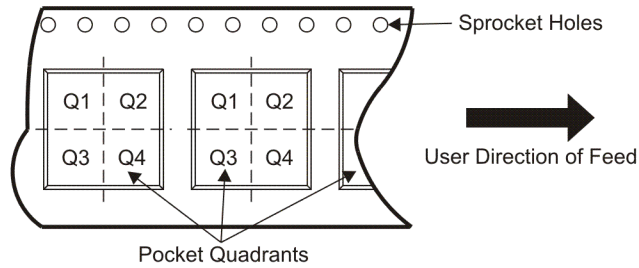
● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC161M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC163M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HCT161M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HCT163M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC161M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74HC163M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74HCT161M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74HCT163M96	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

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Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
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